

CLAIMSWhat is Claimed is:

1           1.    A vehicle for enabling attachment of an optic fiber to a multi-integrated  
2    optic chip in optical communication therewith, and for maintaining alignment of the  
3    fiber at its end adjacent the chip, comprising:

4                a sleeve having a symmetrically-shaped cavity bounded by termini  
5    which respectively interface with the chip and the fiber; and

6                an adhesive disposed within the cavity and symmetrically bonding the  
7    fiber to the chip.

1           2.    A vehicle according to claim 1 wherein:

2                said cavity has an axis and is internally bounded by a wall which is  
3    substantially centered on the axis and which extends from said chip-interfacing  
4    terminus to said fiber-interfacing terminus;

5                said termini are centered on the axis; and

6                a line lying within any plane intersecting the axis at right angles  
7    thereto and terminating in said cavity wall is bisected into two equal segments.

1           3.    A vehicle according to claim 1 wherein said sleeve is configured to fit  
2    onto the chip and is disposed to accept the fiber.

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1           4. A vehicle according to claim 3 wherein:  
 2           said cavity has an axis and is internally bounded by a wall which is  
 3 substantially centered on the axis and which extends from said chip-fitting terminus  
 4 to said fiber-accepting terminus;  
 5           said termini are centered on the axis; and  
 6           a line lying within any plane intersecting the axis at right angles  
 7 thereto and terminating in said cavity wall is bisected into two equal segments.

1           5. A vehicle according to claim 4 wherein said cavity wall slopes from  
 2 said chip-fitting terminus to said fiber-accepting terminus.

1           6. A vehicle according to claim 4 in which said sleeve so controls said  
 2 adhesive as to provide and preserve a symmetrical bonding of the fiber with  
 3 respect to the chip over gravitational and wicking effects.

1           7. A vehicle according to claim 6 in which said cavity wall is shaped as  
 2 a truncated right circular cone.

1           8. A vehicle according to claim 6 in which said cavity wall is shaped as  
 2 a truncated pyramid.

1           9. A vehicle according to claim 4 in which said sleeve is temporarily  
 2 attached to said adhesive and the chip.

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1 10. A vehicle according to claim 4 in which said sleeve is permanently  
2 attached to said adhesive and the chip.

1 11. A method for attaching an optic fiber to an optic chip and for  
2 maintaining alignment of the fiber at its end adjacent the chip, comprising the steps  
3 of:

4 positioning a sleeve having a symmetrically shaped cavity on the chip;  
5 placing an adhesive into the sleeve cavity;  
6 inserting the fiber into the cavity;  
7 securing the fiber to the chip; and  
8 curing the adhesive.

1 12. A method according to claim 11 further comprising the step of aligning  
2 the fiber within the cavity and positioning the fiber end adjacent the chip.

1 13. A method according to claim 11 further comprising the step of  
2 removing the sleeve from the chip after the adhesive has cured.

1 14. A method according to claim 11 further comprising the step of leaving  
2 the sleeve securely on the chip after the adhesive has cured.

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1 15. A method according to claim 11 further comprising the step of  
2 providing the sleeve cavity with a truncated pyramid configuration.

1 16. A method according to claim 11 further comprising the step of  
2 providing the sleeve cavity with a truncated right circular cone configuration.

1 17. A method for attaching an optic fiber to an optic chip and for  
2 maintaining alignment of the fiber at its end adjacent the chip, comprising the steps  
3 of:  
4 utilizing a sleeve having a symmetrically shaped cavity;  
5 placing an adhesive into the sleeve cavity;  
6 positioning the sleeve onto the chip;  
7 inserting the fiber into the cavity;  
8 aligning the fiber within the cavity and positioning the fiber end  
9 adjacent the chip;  
10 securing the fiber to the chip; and  
11 curing the adhesive.

1 18. A method according to claim 17 further comprising the step of  
2 removing the sleeve from the chip after the adhesive has cured.

1 19. A method according to claim 17 further comprising the step of leaving  
2 the sleeve securely on the chip after the adhesive has cured.

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- 1 20. A method according to claim 17 further comprising the step of  
2 providing the sleeve cavity with a truncated pyramid configuration.

- 1 21. A method according to claim 17 further comprising the step of  
2 providing the sleeve cavity with a truncated right circular cone configuration.

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